

AMENDMENTS TO THE CLAIMS

The following listing of claims will replace all prior versions and listings of claims in the application.

LISTING OF CLAIMS

1-11. (Canceled).

12. (Currently Amended) Die bonding equipment comprising:

a semiconductor chip pickup stage onto which a wafer mount frame is loaded;

an alignment stage spaced apart from the semiconductor chip pickup stage;

a chip transfer unit ~~capable of selecting~~ that selects a semiconductor chip from a wafer mount frame loaded on the semiconductor pickup stage and transferring the semiconductor chip from the semiconductor chip pickup stage to the alignment stage;

an inspection unit ~~for inspecting~~ that inspects a status and a position of land patterns on a mount tape during movement of the mount tape for bonding; and

a bonding unit ~~for bonding~~ that bonds a land pattern from the inspection unit to the semiconductor chip from the alignment stage.

13. (Original) The die bonding equipment of claim 12, wherein the inspection unit comprises a charge coupled device (CCD) camera.

14. (Original) The die bonding equipment of claim 12, wherein the chip transfer unit comprises:

a linear reciprocating unit;

a semiconductor chip adsorption unit coupled with the linear reciprocating unit and reciprocating along a path between the semiconductor chip pickup stage and an alignment stage; and

a semiconductor chip tray disposed along the path of the semiconductor chip adsorption unit, the semiconductor chip tray have capacity to receive at least one defective semiconductor chip.

15. (Original) The die bonding equipment of claim 14, wherein the semiconductor chip tray comprises a receiving part on which at least one semiconductor chip is received, the receiving part being formed in one row.

16. (Original) The die bonding equipment of claim 14, wherein the semiconductor chip adsorption unit comprises:

a pair of pulleys spaced apart from each other;

a tension wire rolled on the pair of pulleys;

a chip adsorbing module coupled with the tension wire, for adsorbing and fixing a semiconductor chip with a vacuum pressure; and

a driving motor coupled to one of the pair of pulleys, for reciprocating the tension wire and thereby transferring the chip adsorbing module by a selected distance.

17-20. (Canceled).

21. (Previously Added) A chip transfer unit of die bonding equipment, the chip transfer unit comprises:

a linear reciprocating unit;

a semiconductor chip adsorption unit coupled with the linear reciprocating unit and reciprocating along a first path between a semiconductor chip pickup stage and an alignment stage; and

a semiconductor chip tray disposed along a second path of a semiconductor chip adsorption unit, the semiconductor chip tray having capacity to receive at least one defective semiconductor chip.

22. (Previously Added) The chip transfer unit of claim 21, wherein the semiconductor chip tray comprises a receiving part on which at least one semiconductor chip is received, the receiving part being formed in one row.

23. (Previously Added) The chip transfer unit of claim 21, wherein the semiconductor chip adsorption unit comprises:

a pair of pulleys spaced apart from each other;

a tension wire rolled on the pair of pulleys;

a chip adsorbing module coupled with the tension wire, for adsorbing and fixing the semiconductor chip with a vacuum pressure; and

a driving motor coupled to one of the pair of pulleys, for reciprocating the tension wire and thereby transferring the chip adsorbing module by a selected distance.

24. (New) The die bonding equipment of claim 12, wherein, the inspection unit is positioned between a mount stacker and a bonding unit camera.

25. (New) The die bonding equipment of claim 12, wherein, the inspection unit is positioned over guide rails.